

RJK2508DPK

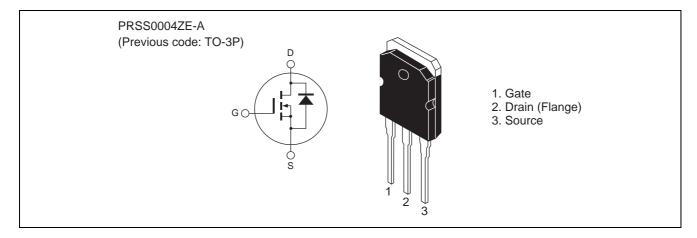
Silicon N Channel MOS FET High Speed Power Switching

REJ03G0508-0200 Rev.2.00 Feb.10.2005

Features

- Low on-resistance
- Low leakage current
- High speed switching

Outline



Absolute Maximum Ratings

 $(Ta = 25^{\circ}C)$

ltem	Symbol	Ratings	Unit
Drain to Source voltage	V _{DSS}	250	V
Gate to Source voltage	V_{GSS}	±30	V
Drain current	I _D	50	Α
Drain peak current	I _{D (pulse)} Note1	100	Α
Body-Drain diode reverse Drain current	I _{DR}	50	Α
Body-Drain diode reverse Drain peak current	I _{DR (pulse)} Note1	100	Α
Avalanche current	I _{AP} Note3	17	Α
Avalanche energy	E _{AR} Note3	18.0	mJ
Channel dissipation	Pch Note2	150	W
Channel to case thermal impedance	θch-c	0.833	°C/W
Channel temperature	Tch	150	°C
Storage temperature	Tstg	-55 to +150	°C

Notes: 1. $PW \le 10 \mu s$, duty cycle $\le 1\%$

2. Value at $Tc = 25^{\circ}C$

3. STch = 25° C, Tch $\leq 150^{\circ}$ C

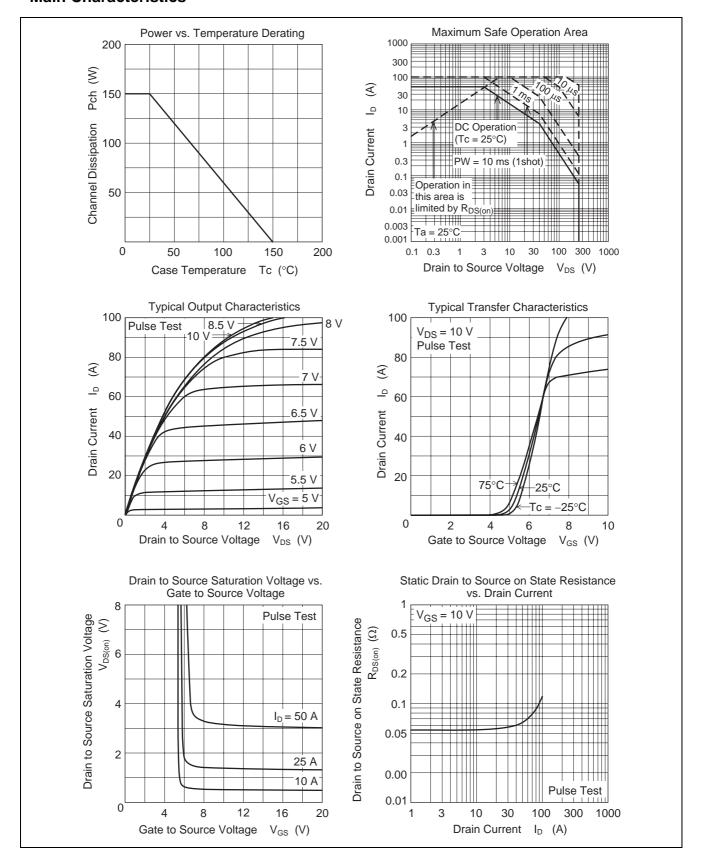
Electrical Characteristics

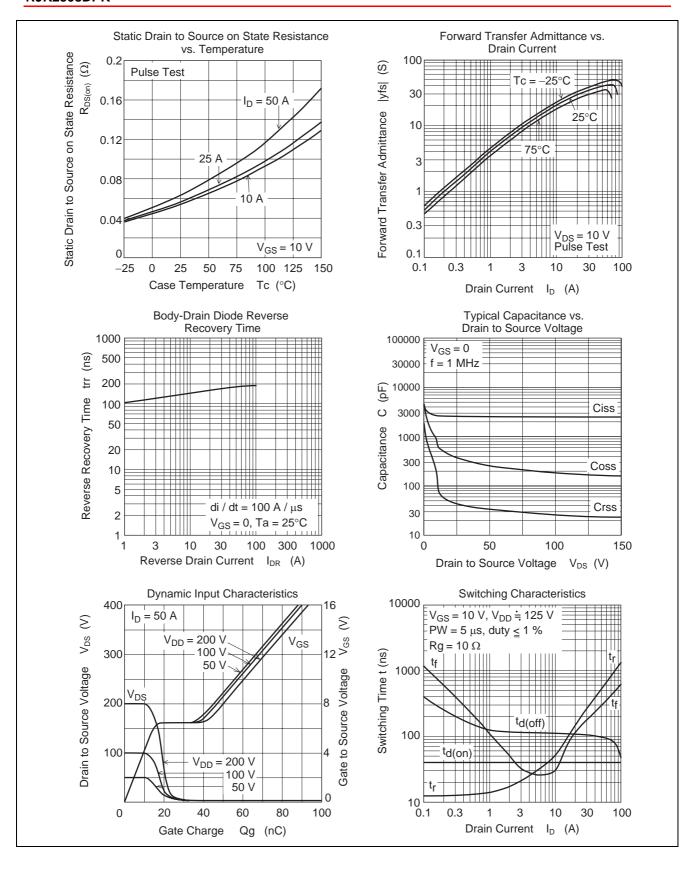
 $(Ta = 25^{\circ}C)$

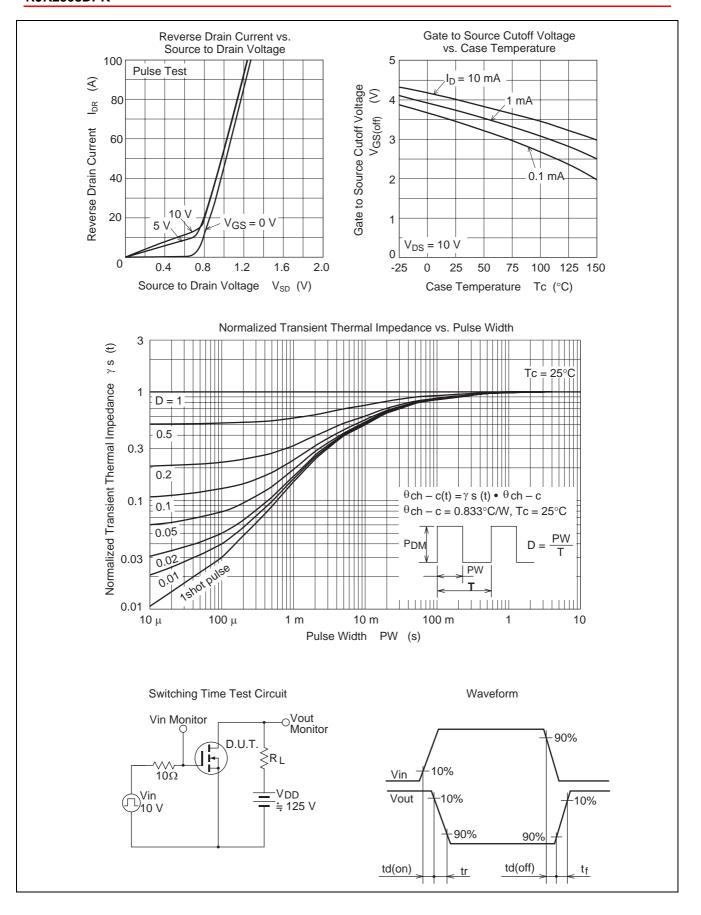
Item	Symbol	Min	Тур	Max	Unit	Test conditions
Drain to Source breakdown voltage	$V_{(BR)DSS}$	250		_	V	$I_D = 10 \text{ mA}, V_{GS} = 0$
Zero Gate voltage Drain current	I _{DSS}	_	_	1	μΑ	$V_{DS} = 250 \text{ V}, V_{GS} = 0$
Gate to Source leak current	I _{GSS}	_	_	±0.1	μΑ	$V_{GS} = \pm 30 \text{ V}, V_{DS} = 0$
Gate to Source cutoff voltage	$V_{GS(off)}$	3.0	_	4.5	V	$V_{DS} = 10 \text{ V}, I_{D} = 1 \text{ mA}$
Forward transfer admittance	yfs	19	32	_	S	$I_D = 25 \text{ A}, V_{DS} = 10 \text{ V}^{\text{Note4}}$
Static Drain to Source on state resistance	R _{DS(on)}	_	0.056	0.064	Ω	$I_D = 25 \text{ A}, V_{GS} = 10 \text{ V}^{Note4}$
Input capacitance	Ciss		2600		pF	V _{DS} = 25 V
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Output capacitance	Coss		370	_	pF	V _{GS} = 0 f = 1 MHz
Reverse transfer capacitance	Crss	_	43	_	pF	
Turn-on delay time	t _{d(on)}	_	40	_	ns	I _D = 25 A
Rise time	t _r	_	210	_	ns	$V_{GS} = 10 \text{ V}$ $R_{L} = 5 \Omega$ $Rg = 10 \Omega$
Turn-off delay time	$t_{d(off)}$	_	110	_	ns	
Fall time	t _f	_	145	_	ns	
Total Gate charge	Qg	_	60	_	nC	V _{DD} = 200 V
Gate to Source charge	Qgs	_	15	_	nC	V _{GS} = 10 V I _D = 50 A
Gate to Drain charge	Qgd	_	26	_	nC	
Body-Drain diode forward voltage	V_{DF}	_	1.0	1.5	V	$I_F = 50 \text{ A}, V_{GS} = 0^{\text{Note4}}$
Body-Drain diode reverse recovery time	trr	_	180	_	ns	$I_F = 50 \text{ A}, V_{GS} = 0$
Body-Drain diode reverse recovery charge	Qrr	_	1.2	_	μС	diF/dt = 100 A/μs

Notes: 4. Pulse test

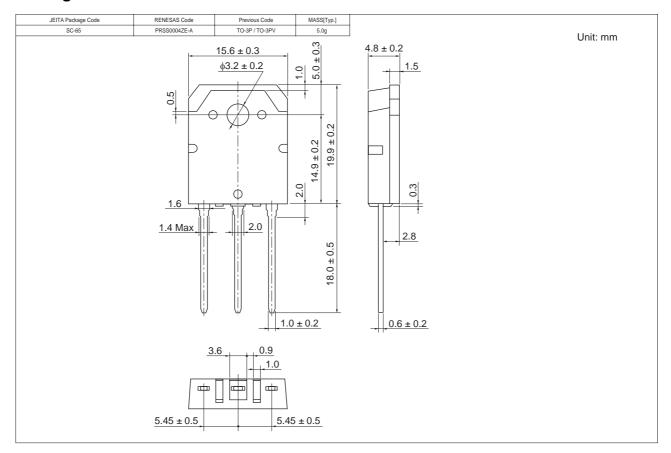
Main Characteristics







Package Dimensions



Ordering Information

Part Name	Quantity	Shipping Container
RJK2508DPK-E	30 pcs	Plastic magazine

Note: For some grades, production may be terminated. Please contact the Renesas sales office to check the state of production before ordering the product.

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